

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	51	pressure adj roller and 257\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/04/11 16:12
L3	18	dual adj blade and 257\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/04/11 16:12
S1	119	warp\$3 and 257/734	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/04/11 08:50
S2	1	("6825108").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/03/21 11:04
S3	1	("6242300").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/03/21 11:04
S4	1	("6168984").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/03/21 14:18
S5	1	"20030214011"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/03/21 14:18
S6	0	mold adj gate and lead adj package and 257/734	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/03/23 13:00
S7	0	mold adj gate and lead adj package and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/03/23 13:01

S8	0	molded adj gate and lead adj package and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/03/23 13:01
S9	2	molded adj gate and lead and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/03/23 13:01
S10	1	double adj bump adj wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/04/11 08:51
S11	1601	(257/738).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/04/11 16:05